US009411230B2

(12) **United States Patent**
Takizawa et al.

(10) **Patent No.: US 9,411,230 B2**
(45) **Date of Patent: Aug. 9, 2016**

(54) **PATTERN FORMING METHOD, ELECTRON BEAM-SENSITIVE OR EXTREME ULTRAVIOLET-SENSITIVE COMPOSITION, RESIST FILM, METHOD FOR MANUFACTURING ELECTRONIC DEVICE USING THE SAME, AND ELECTRONIC DEVICE**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 14 days.

(21) Appl. No.: **14/227,344**

(22) Filed: **Mar. 27, 2014**

(65) **Prior Publication Data**

US 2014/0212796 A1 Jul. 31, 2014

Related U.S. Application Data

(63) Continuation of application No. PCT/JP2012/074315, filed on Sep. 14, 2012.

(30) **Foreign Application Priority Data**

Sep. 30, 2011 (JP) 2011-218546

(51) **Int. Cl.**

G03F 7/038	(2006.01)
G03F 7/32	(2006.01)
G03F 7/004	(2006.01)
G03F 7/039	(2006.01)
G03F 7/11	(2006.01)
G03F 7/20	(2006.01)
G03F 7/40	(2006.01)

(52) **U.S. Cl.**

CPC ***G03F 7/0388*** (2013.01); ***G03F 7/0045*** (2013.01); ***G03F 7/0046*** (2013.01); ***G03F 7/038*** (2013.01); ***G03F 7/0392*** (2013.01); ***G03F 7/0397*** (2013.01); ***G03F 7/11*** (2013.01); ***G03F 7/2041*** (2013.01); ***G03F 7/325*** (2013.01); ***G03F 7/405*** (2013.01)

(58) **Field of Classification Search**

CPC ... G03F 7/0045; G03F 7/0046; G03F 7/0388; G03F 7/325; G03F 7/2041; G03F 7/038; G03F 7/0392; G03F 7/11; G03F 7/405; G03F 7/0397; G03F 7/2059; G03F 7/2004

USPC 430/9, 18, 270.1, 288.1, 325

See application file for complete search history.

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(57) **ABSTRACT**

There is provided a pattern forming method comprising (1) a step of forming a film by using an electron beam-sensitive or extreme ultraviolet-sensitive resin composition, (2) a step of exposing the film by using an electron beam or an extreme ultraviolet ray, and (3) a step of developing the exposed film by using an organic solvent-containing developer, wherein the electron beam-sensitive or extreme ultraviolet-sensitive resin composition contains (A) a resin containing (R) a repeating unit having a structural moiety capable of decomposing upon irradiation with an electron beam or an extreme ultraviolet ray to generate an acid, and (B) a solvent.

25 Claims, No Drawings